



FLIP CHIP MODULES TEST SPECS

TYPE: R303

INTERGRATING ONE-SHOT

TEST	CONDITIONS	MINIMUM	MAXIMUM
INPUT CURRENT	DCD GATE (PIN T)	1.5-2.0 MA	/
	DIRECT (PIN V)	.75-1.0 MA	/
OUTPUT CURRENT	IOMA LOADS (PINS H,F)	9.0 MA	11.0 MA
	ONE, ZERO OUTPUTS (PINS D,E)	1.5 MA	2.2 MA
LOWER LEVEL	IOMA LOADS (PINS H,F)	3.2 V	3.8 V
	ONE, ZERO OUTPUTS (PINS D,E)	3.2 V	3.8 V
GATE THRESHOLD	FLIP-FLOP INPUT TO DCD PULSE INPUT ; LEVEL INPUT THRESHOLD	1.5 V	2.5 V
DELAY	EXTERNAL 1 MFD (PIN J)	800-1600 μ SEC	18-27 MSEC
	MINIMUM	≤ 3.5 μ SEC	* μ SEC
	PIN K	* μ SEC	* μ SEC
	PIN L	* μ SEC	* MSEC
	PIN M	* MSEC	* MSEC
	PIN N	* MSEC	≈ 900 MSEC
JITTER	PIN M, 10 MSEC DELAY	/	1.3 %
CHANGE WITH $\pm 20\%$ VOLTAGE	PIN M, 10 MSEC DELAY	/	1.9 %

* RANGES MUST OVERLAP.

12/19/66

TECHNICAL INFORMATION

Instruction literature and technical bulletins are available on all digital products, if you would like to be added to our mailing list for this type of material or if you have any questions about the equipment you have purchased, please contact the nearest Digital Sales Office.

MAINTENANCE INFORMATION

Repair of printed circuitry should be done with a low voltage, fairly cool soldering iron to prevent damage to the transistors and keep the copper from lifting. Oscilloscopes used to troubleshoot a module or system should be grounded to prevent damaging transients.